

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5004785

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUNG-FUNG LIN	05/23/2018
CHENG-WEI CHOU	05/23/2018
SZU-YAO CHANG	05/23/2018
CHENG-TAO CHOU	05/23/2018
HSIU-MING CHEN	05/23/2018
RECEIVING PARTY DATA	
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State/Country:	TAIWAN
Postal Code:	30077
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16005964
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NAME OF SUBMITTER:	CHRISTOPHER SMITH
SIGNATURE:	/Christopher Smith/
DATE SIGNED:	06/12/2018
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Yung-Fung LIN, Cheng-Wei CHOU, Szu-Yao CHANG, Cheng-Tao CHOU, and Hsiu-Ming Chen hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR STRUCTURE, HIGH ELECTRON MOBILITY TRANSISTORS, AND METHODS FOR FABRICATING SEMICONDUCTOR STRUCTURE

Filed: 12-JUN-2018 Serial No. 16005964

Executed on: 23 MAY 2018;

WHEREAS, Vanguard International Semiconductor Corporation of 123, Park Ave-3rd, Science - Based Industrial Park, Hsinchu, Taiwan 30077, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Yung-Fung LIN
Yung-Fung LIN

5/23/2018
Date

Cheng-Wei CHOU
Cheng-Wei Chou

5/23/2018
Date

ASSIGNMENT

Szu-Yao Chang
Szu-Yao CHANG

5/23/2018

Date

Cheng-Tao Chou
Cheng-Tao CHOU

5/23/2018

Date

Hsiu-Ming Chen
Hsiu-Ming Chen

5/23/2018

Date